



**3D InCites, TechSearch International and SEMI Announce the Winners
of the 2014 3D InCites Awards Program**

*Awards a \$2,500 scholarship to a graduate of SEMI High Tech U; Contributes
\$2,500 to the Frances B. Hugle 'Women in Engineering' Scholarship Fund*

Phoenix – July 16, 2014 – [3D InCites](#), the premier online content source for reliable 3D technology information; SEMI, the global industry association serving the nano- and microelectronics manufacturing supply chains; and [TechSearch International](#), the leading market research firm for advanced semiconductor packaging technology, today announced the winners of the 2014 3D InCites Awards program, established to recognize achievements to further the commercialization of 2.5D and 3D IC technologies. Proceeds of the 2014 awards program funded a newly formed 3D InCites STEM Scholarship program, which this year will award a \$2,500 scholarship to a graduate of the SEMI High Tech U program. Twenty-five hundred dollars was also contributed to the IEEE Frances B. Hugle Engineering Scholarship fund.

Awards were presented at a breakfast ceremony hosted by Impress Labs and sponsored by Micron on Thursday, July 10, 2014 at the Impress Lounge during SEMICON West. The event featured guest speaker Bryan Black, Senior Fellow, AMD, who has led AMD's die stacking program for the past seven years. Black talked about the future of die stacking and where the benefits lie within the context of mainstream computing CPUs, APUs, and GPUs.

Micron's Rodney Morgan, VP procurement, presented a \$2,500 check on behalf of the 3D InCites STEM Scholarship program to Karen Savala, President, SEMI Americas, to represent the \$2,500 scholarship that will be awarded to a graduate of SEMI High Tech U. David Kirsch, VP and General Manager, EV Group North America, presented a \$2,500 check to Jan Vardaman, TechSearch International, representing the donation to the IEEE Frances B. Hugle Engineering Scholarship. The charitable donations were made possible by the sponsors of the 2014 3D InCites Awards, including Platinum Sponsor, EV Group; Breakfast Sponsor, Micron; and Silver Sponsors, Mentor Graphics and Rudolph Technologies.

A panel of 15 industry expert judges determined the winners from a field of 14 nominees in five categories. Additionally, an online "popular vote" decided the winner of the Reader's Choice Award from the same field of nominees.

The 2014 3D InCites Awards winners are:

- **2.5D/3D Design Tools**
[E-System Design](#): Sphinx 3D Path Finder (“3DPF”) V3.0
- **2.5D/3D Devices**
SORIN CRM: 3D IC Module for Active Medical Implant
- **2.5D/3D Manufacturing Equipment**
SSEC: WaferEtch TSV Revealer
- **2.5D/3D Processes**
SPTS: Blanket Silicon Etch Process for Via Reveal
- **Inspection/Metrology Tools**
Fogale: TMAP DUAL 3D 300 A
- **Reader’s Choice Award**
Novati Technologies: Silicon Interposer Module

To learn more about the winning products and processes, [read about them here on 3D InCites](#). For more information on how to participate in the awards program, or become a sponsor, visit the [3D InCites Awards Web page](#).

Link to the award photos: [Photos](#)

We invite those interested in making donations directly to the Frances B. Hugle Engineering Scholarship fund to visit iee.org/donate and select the IEEE WIE Frances B. Hugle Memorial Fund. Those interested in sponsoring SEMI High Tech U. should email Lisa Anderson (landerson@semi.org).

About 3D InCites

3D InCites is an online content source founded in 2009 in an effort to stir up interest in 3D IC integration and 3D packaging technologies. For 3D integration to happen, open collaboration across the supply chain is required. Therefore, 3D InCites strives to inform key decision-makers about progress in technology development, design, standards, and infrastructure in order to realize commercial production of 2.5D and 3D technologies. 3D InCites is powered by Impress Labs, a global creative and marketing communications agency specializing in building brands for technology companies in the semiconductor, solar energy and life science industries. For more information, visit www.3DInCites.com.

About TechSearch International

TechSearch International, Inc., founded in 1987, is the market research leader specializing in technology trends, microelectronics, packaging, and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International

professionals have an extensive network of more than 15,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887, fax: 512-372-8889, or <http://www.techsearchinc.com>.

About SEMI

SEMI is the global industry association serving the nano- and microelectronics manufacturing supply chains. Our 1,900 member companies are the engine of the future, enabling smarter, faster, and more economical products that improve our lives. Since 1970, SEMI has been committed to helping members grow more profitably, create new markets, and meet common industry challenges. SEMI maintains offices in Bangalore, Beijing, Berlin, Brussels, Grenoble, Hsinchu, Moscow, San Jose, Seoul, Shanghai, Singapore, Tokyo and Washington, D.C. For more information, visit www.semi.org.

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